

AMENDMENTS TO THE CLAIMS

Listing Of Claims

Claims 1-56 (Canceled)

57. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe; and

a plastic body comprising a first polymer member ~~on~~ encapsulating the die ~~or~~ and a portion of the leadframe, and a second polymer member encapsulating the first polymer member, the first polymer member comprising a molded material and at least one filler, the first polymer member, the molded material and the filler having a selected geometry configured to reduce thermo mechanical stresses in the package.

~~provide substantially equal volumes of the second polymer member on either side of the leadframe.~~

58. (currently amended) The semiconductor package of claim 57 wherein the molded material comprises a cured molding compound.

~~first polymer member includes a filler configured to provide a selected characteristic of the package.~~

59. (canceled)

60. (currently amended) The semiconductor package of claim 57 wherein the second polymer member comprises a second filler.

~~first polymer member includes a filler configured to provide an increased rigidity for the package.~~

61. (currently amended) The semiconductor package of claim 57 wherein the first polymer member has a selected geometry.
~~comprises an epoxy resin.~~

62. (currently amended) The semiconductor package of claim 57 wherein the first polymer member has selected dimensions.
~~comprises a tape material~~

63. (currently amended) The semiconductor package of claim 57 wherein the die includes wire bonds and the first polymer member encapsulates the ~~die~~ wire bonds.

64. (currently amended) The semiconductor package of claim 57 wherein the first polymer member and the second polymer member ~~both~~ comprise a ~~same~~ molding compound containing a filler.

65. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe;

a plurality of wire bonds bonded to the die and the leadframe;

a first polymer member ~~on~~ encapsulating the die, the wire bonds, and at least a portion of ~~on~~ the leadframe;
and

a second polymer member encapsulating the first polymer member;

the first polymer member comprising a rigid molded material having a selected geometry and at least one filler configured to reduce thermo-mechanical stresses in the second polymer member.

~~provide a selected characteristic for the package.~~

66. (previously presented) The semiconductor package of claim 65 wherein the selected geometry provides substantially equal volumes of a molding compound of the second polymer member on either side of the leadframe.

67. (currently amended) The semiconductor package of claim 65 wherein the ~~selected geometry and the filler are~~ is configured to increase a rigidity of the first polymer member.

~~reduce a package bow.~~

68. (currently amended) The semiconductor package of claim 65 wherein the selected geometry ~~and the filler are~~ is configured to reduce a package bow or warpage.

69. (currently amended) The semiconductor package of claim 65 wherein the ~~first polymer member and the second polymer member comprise a same~~ the rigid molded material.

~~molding compound.~~

70. (currently amended) The semiconductor package of claim 65 wherein the first polymer member ~~and the second polymer member~~ comprises a cured B-stage epoxy.

~~a same molded plastic.~~

71. (currently amended) A semiconductor package comprising:

a leadframe having a first side and a second side;

a die on the leadframe;

a plurality of polymer members on ~~the die or~~ the leadframe; and

a plastic body comprising a molding compound encapsulating the polymer members and at least a portion of the leadframe, the plastic body having a first portion on the first side having a first volume and a second portion on the second side having a second volume;

the polymer members having a selected volume configured to equalize the first volume and the second volume and to reduce thermo-mechanical stresses in the package during molding of the plastic body.

72. (currently amended) The semiconductor package of claim 71 wherein the polymer members comprises a material selected from the group consisting of epoxy, silicone, room temperature vulcanizing (RTV) and polyimide.

73. (currently amended) The semiconductor package of claim 71 wherein the polymer members comprises a tape material.

74. (currently amended) The semiconductor package of claim 71 wherein the polymer members comprise a filler.
~~encapsulates the die.~~

75. (currently amended) The semiconductor package of claim 71 wherein the polymer members are located on opposing sides of the die.

~~leadframe has a lead on chip configuration.~~

76. (currently amended) The semiconductor package of claim 71 wherein ~~the~~ each polymer member has a generally rectangular shape.

~~die is attached and wire bonded to the leadframe.~~

77. (currently amended) The semiconductor package of claim 71 wherein the polymer members comprises an electrically insulating cured material.

~~the molding compound.~~

78. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe; ~~and~~

a plurality of wire bonds bonded to the die and to the leadframe;

a molded first polymer member ~~on~~ encapsulating the die, ~~or~~ the wire bonds and a portion of the leadframe, including the first polymer member comprising a first molding compound and having a first filler, the first polymer member, the first molding compound and the first filler configured to reduce thermo-mechanical stresses in the package; and

a molded second polymer member ~~on~~ encapsulating the first polymer member, the second polymer member comprising a second molding compound and a second filler.

~~and the leadframe;~~

~~the first polymer member and the filler configured to provide a selected characteristic in the second polymer member.~~

79. (currently amended) The semiconductor package of claim 78 wherein the first molding compound comprises a rigid plastic.

~~selected characteristic comprises increased rigidity.~~

80. (currently amended) The semiconductor package of claim 78 wherein the second polymer member comprises substantially equal volumes of a the second molding compound on either side of the leadframe.

81. (currently amended) The semiconductor package of claim 78 wherein the first polymer member has a selected geometry and selected dimensions.

~~substantially encapsulates the die.~~

82. (currently amended) The semiconductor package of claim 78 wherein the first polymer member and the second polymer member comprise a cured B-stage epoxy.

~~substantially encapsulates the first polymer member.~~